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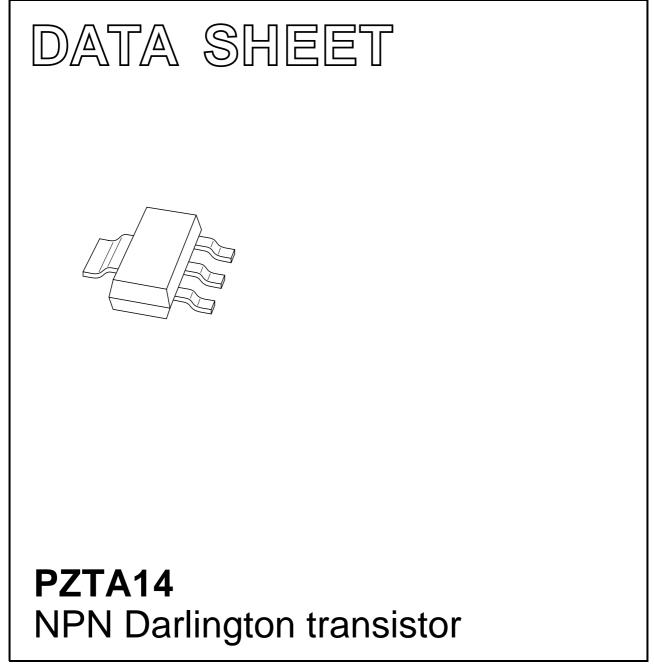
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1997 Sep 04 1999 Apr 14



PZTA14

FEATURES

- High current (max. 500 mA)
- Low voltage (max. 30 V).

APPLICATIONS

• Pre-amplifiers requiring high input impedance.

DESCRIPTION

NPN Darlington transistor in a SOT223 plastic package. PNP complement: PZTA64.

PINNING

PIN	DESCRIPTION	
1	base/input	
2, 4	collector/output	
3	emitter/ground	

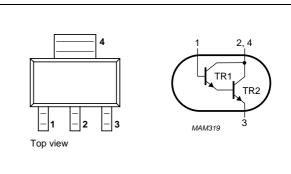


Fig.1 Simplified outline (SOT223) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	30	V
V _{CES}	collector-emitter voltage	$V_{BE} = 0$	-	30	V
V _{EBO}	emitter-base voltage	open collector	-	10	V
I _C	collector current (DC)		-	500	mA
I _{CM}	peak collector current		-	800	mA
I _B	base current (DC)		-	200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	-	1.25	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

PZTA14

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	100	K/W
R _{th j-s}	thermal resistance from junction to soldering point		19	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

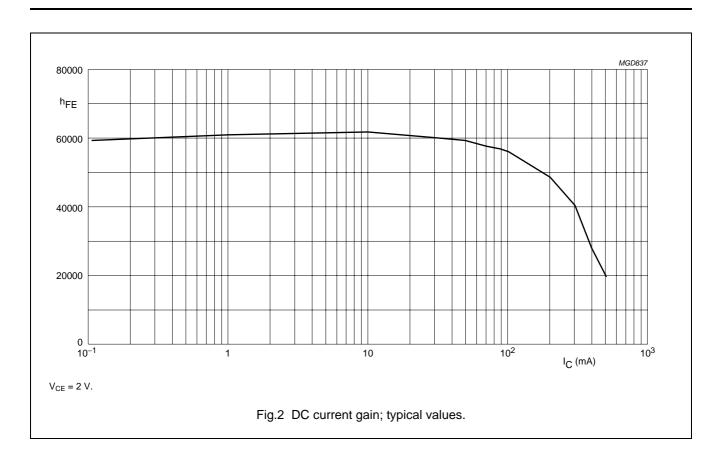
CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

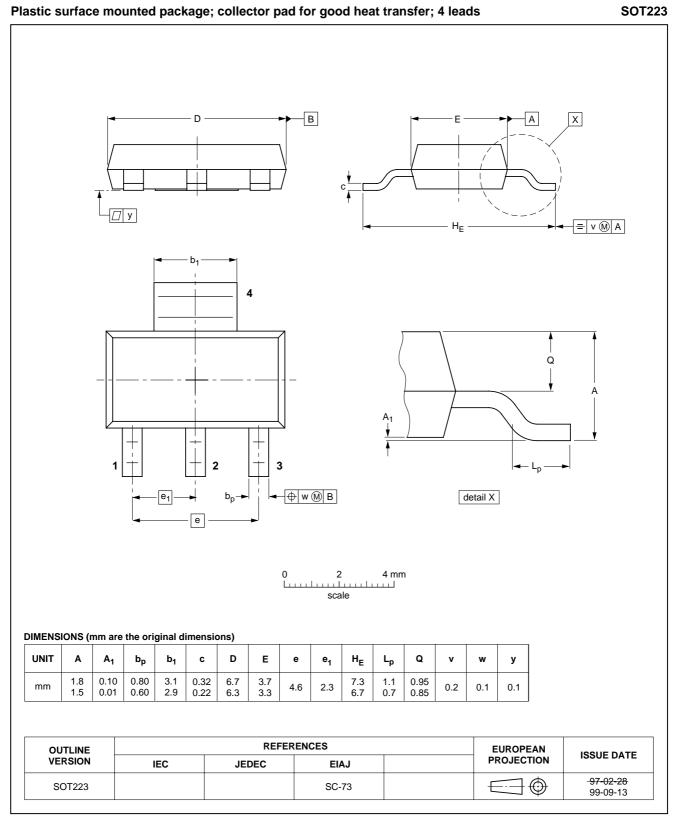
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 30 V	-	100	nA
I _{CES}	collector cut-off current	V _{BE} = 0; V _{CE} = 30 V	-	100	nA
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = 10 V	-	100	nA
h _{FE}	DC current gain	V _{CE} = 5 V; (see Fig.2)			
		I _C = 10 mA	10000	-	
		I _C = 100 mA	20000	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 100 mA; I _B = 0.1 mA	-	1.5	V
V _{BEon}	base-emitter on-state voltage	I _C = 100 mA; V _{CE} = 5 V	-	2	V
f _T	transition frequency	$I_{C} = 10 \text{ mA}; V_{CE} = 5 \text{ V}; \text{ f} = 100 \text{ MHz}$	125	-	MHz

PZTA14

NPN Darlington transistor



PACKAGE OUTLINE



PZTA14

PZTA14

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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